

## NCE N-Channel Super Trench II Power MOSFET

### Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

### Application

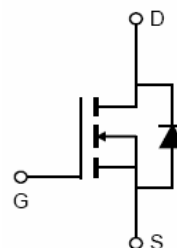
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### General Features

- $V_{DS} = 100V, I_D = 62A$   
 $R_{DS(ON)} = 4.4m\Omega$ , typical @  $V_{GS} = 10V$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

TO-220F



Schematic Diagram

### Package Marking and Ordering Information

| Device Marking | Device      | Device Package | Reel Size | Tape width | Quantity |
|----------------|-------------|----------------|-----------|------------|----------|
| NCEP039N10F    | NCEP039N10F | TO-220F        | -         | -          | -        |

### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

| Parameter                                             | Symbol                   | Limit      | Unit                |
|-------------------------------------------------------|--------------------------|------------|---------------------|
| Drain-Source Voltage                                  | $V_{DS}$                 | 100        | V                   |
| Gate-Source Voltage                                   | $V_{GS}$                 | $\pm 20$   | V                   |
| Drain Current-Continuous (Package Limited)            | $I_D$                    | 62         | A                   |
| Drain Current-Continuous( $T_C = 100^\circ\text{C}$ ) | $I_D(100^\circ\text{C})$ | 45         | A                   |
| Pulsed Drain Current <sup>(Note 1)</sup>              | $I_{DM}$                 | 248        | A                   |
| Maximum Power Dissipation                             | $P_D$                    | 40         | W                   |
| Derating factor                                       |                          | 0.27       | W/ $^\circ\text{C}$ |
| Avalanche Current <sup>(Note 1)</sup>                 | $I_{AR}$                 | 55         | A                   |
| Single pulse avalanche energy <sup>(Note 5)</sup>     | $E_{AS}$                 | 1156       | mJ                  |
| Operating Junction and Storage Temperature Range      | $T_J, T_{STG}$           | -55 To 175 | $^\circ\text{C}$    |

### Thermal Characteristic

|                                                          |                 |      |                    |
|----------------------------------------------------------|-----------------|------|--------------------|
| Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup> | $R_{\theta JC}$ | 3.75 | $^\circ\text{C/W}$ |
|----------------------------------------------------------|-----------------|------|--------------------|

**Electrical Characteristics ( $T_C=25^{\circ}\text{C}$  unless otherwise noted)**

| Parameter                                     | Symbol              | Condition                                                                                    | Min | Typ  | Max  | Unit |
|-----------------------------------------------|---------------------|----------------------------------------------------------------------------------------------|-----|------|------|------|
| Off Characteristics                           |                     |                                                                                              |     |      |      |      |
| Drain-Source Breakdown Voltage                | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA                                                    | 100 |      | -    | V    |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> =100V, V <sub>GS</sub> =0V                                                   | -   | -    | 1    | μA   |
| Gate-Body Leakage Current                     | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                                   | -   | -    | ±100 | nA   |
| On Characteristics <sup>(Note 3)</sup>        |                     |                                                                                              |     |      |      |      |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                     | 2.0 | 3.0  | 4.0  | V    |
| Drain-Source On-State Resistance              | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =31A                                                    | -   | 4.4  | 4.8  | mΩ   |
| Forward Transconductance                      | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =31A                                                     |     | 90   | -    | S    |
| Dynamic Characteristics <sup>(Note4)</sup>    |                     |                                                                                              |     |      |      |      |
| Input Capacitance                             | C <sub>iss</sub>    | V <sub>DS</sub> =50V, V <sub>GS</sub> =0V,<br>F=1.0MHz                                       | -   | 6400 | -    | PF   |
| Output Capacitance                            | C <sub>oss</sub>    |                                                                                              | -   | 585  | -    | PF   |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |                                                                                              | -   | 26   | -    | PF   |
| Switching Characteristics <sup>(Note 4)</sup> |                     |                                                                                              |     |      |      |      |
| Turn-on Delay Time                            | t <sub>d(on)</sub>  | V <sub>DD</sub> =50V, I <sub>D</sub> =31A<br>V <sub>GS</sub> =10V, R <sub>G</sub> =1.6Ω      | -   | 20   | -    | nS   |
| Turn-on Rise Time                             | t <sub>r</sub>      |                                                                                              | -   | 11.5 | -    | nS   |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> |                                                                                              | -   | 48   | -    | nS   |
| Turn-Off Fall Time                            | t <sub>f</sub>      |                                                                                              | -   | 10   | -    | nS   |
| Total Gate Charge                             | Q <sub>g</sub>      | V <sub>DS</sub> =50V, I <sub>D</sub> =31A,<br>V <sub>GS</sub> =10V                           | -   | 102  | -    | nC   |
| Gate-Source Charge                            | Q <sub>gs</sub>     |                                                                                              | -   | 36   |      | nC   |
| Gate-Drain Charge                             | Q <sub>gd</sub>     |                                                                                              | -   | 26   |      | nC   |
| Drain-Source Diode Characteristics            |                     |                                                                                              |     |      |      |      |
| Diode Forward Voltage <sup>(Note 3)</sup>     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =31A                                                     | -   |      | 1.2  | V    |
| Diode Forward Current <sup>(Note 2)</sup>     | I <sub>S</sub>      |                                                                                              | -   | -    | 62   | A    |
| Reverse Recovery Time                         | t <sub>rr</sub>     | T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub><br>di/dt = 100A/μs <sup>(Note3)</sup> | -   | 76   | -    | nS   |
| Reverse Recovery Charge                       | Q <sub>rr</sub>     |                                                                                              | -   | 150  | -    | nC   |

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition :  $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, L=0.5\text{mH}, R_g=25\Omega$

## Typical Electrical and Thermal Characteristics

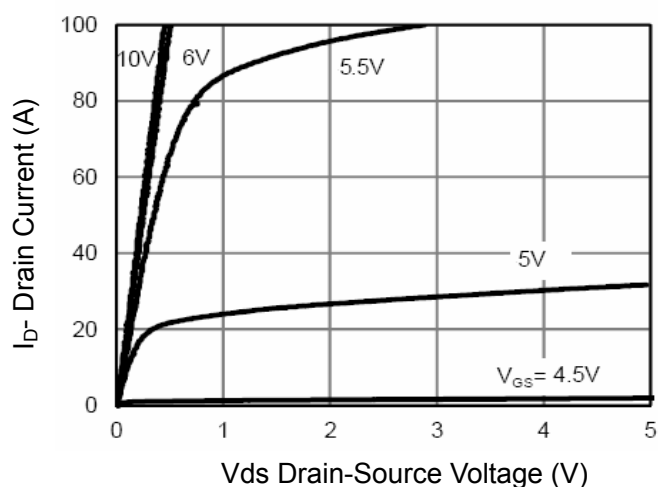


Figure 1 Output Characteristics

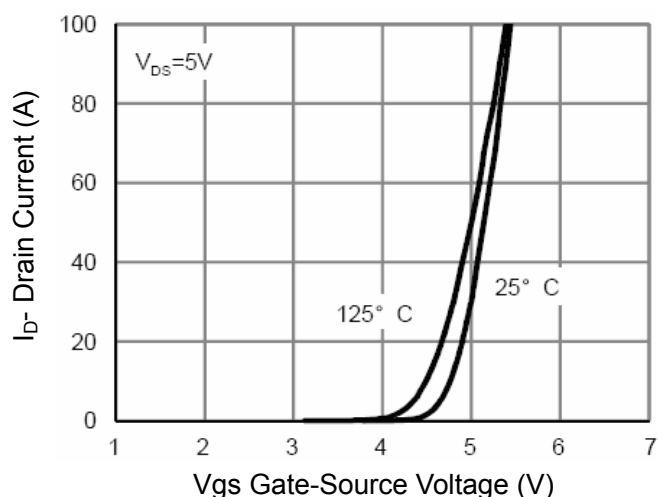


Figure 2 Transfer Characteristics

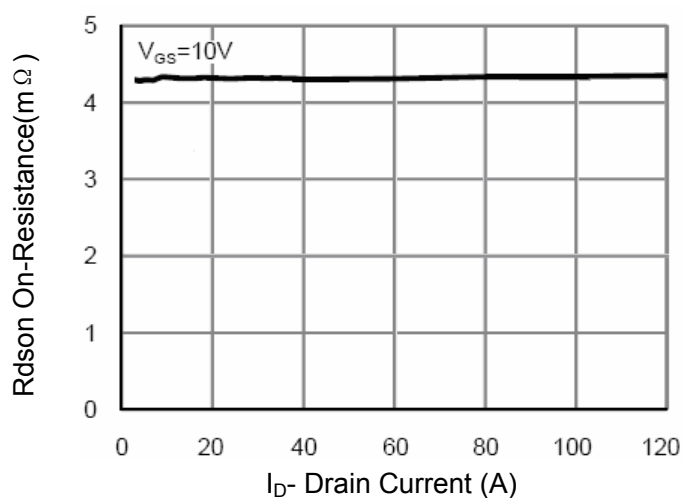


Figure 3 Rdson- Drain Current

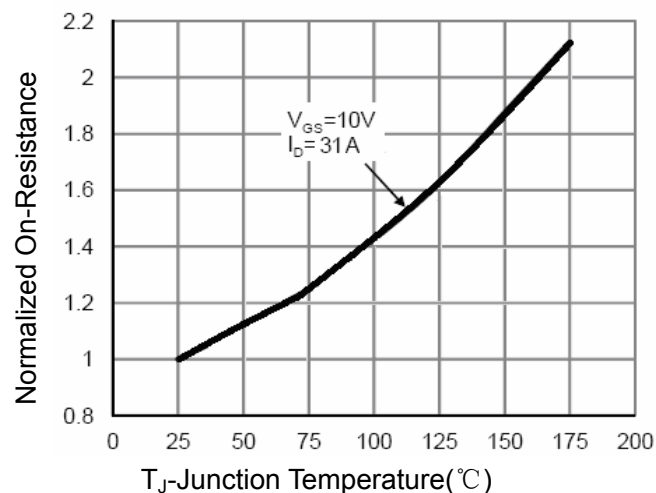


Figure 4 Rdson-Junction Temperature

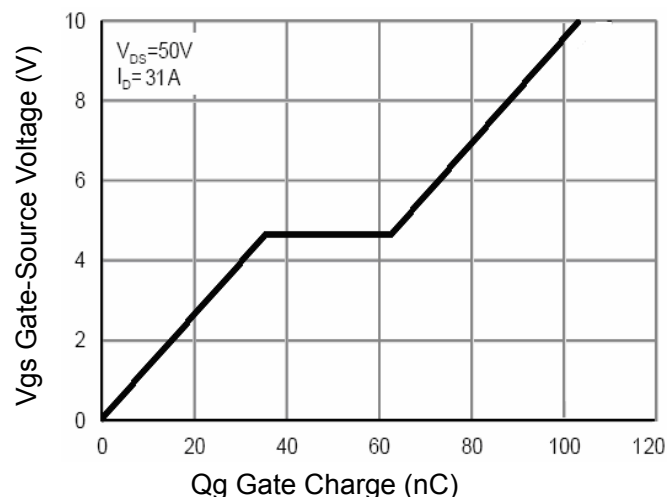


Figure 5 Gate Charge

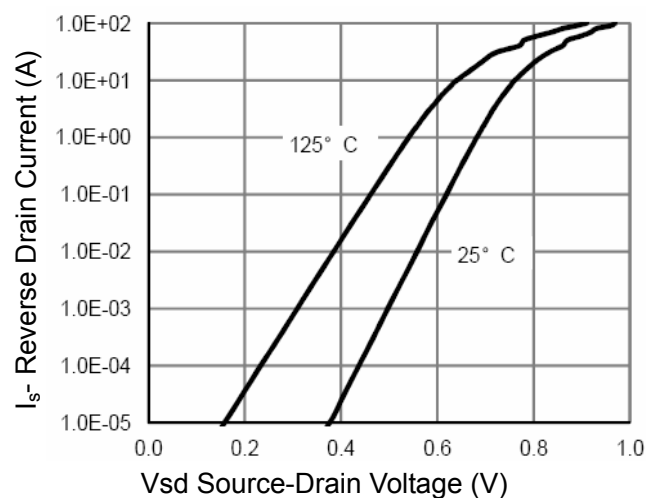


Figure 6 Source- Drain Diode Forward

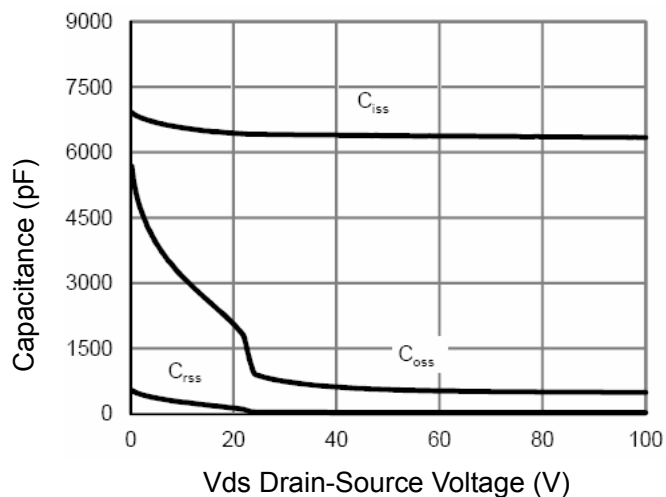


Figure 7 Capacitance vs Vds

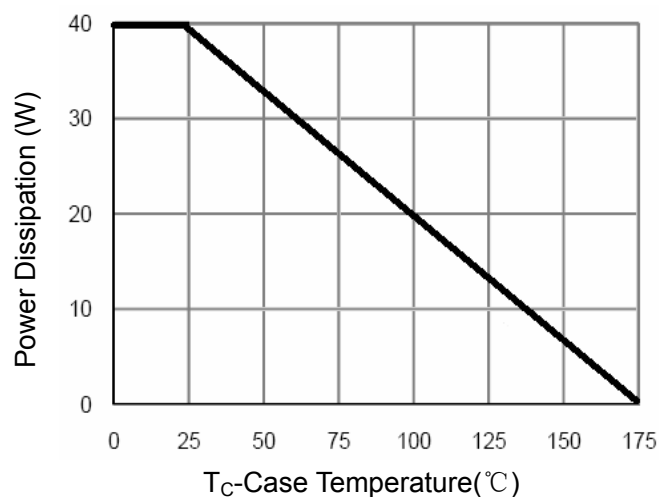


Figure 9 Power De-rating

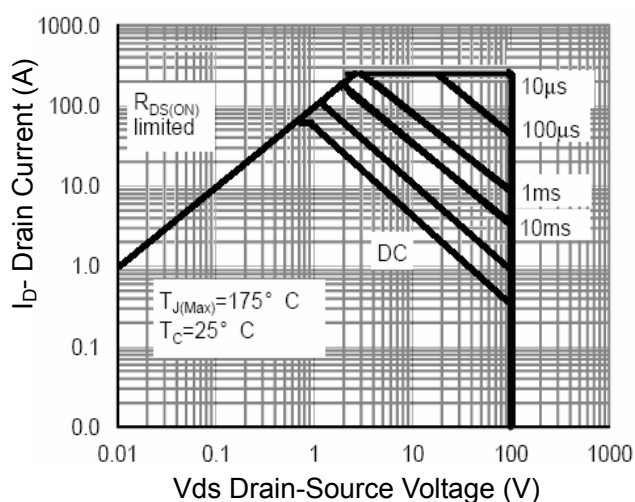


Figure 8 Safe Operation Area

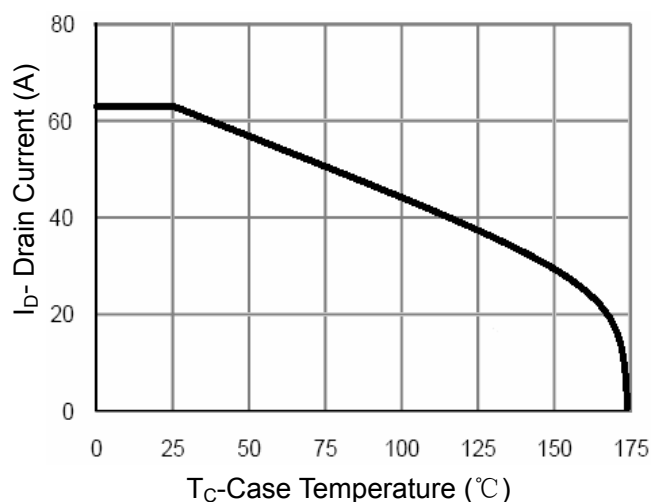


Figure 10 Current De-rating

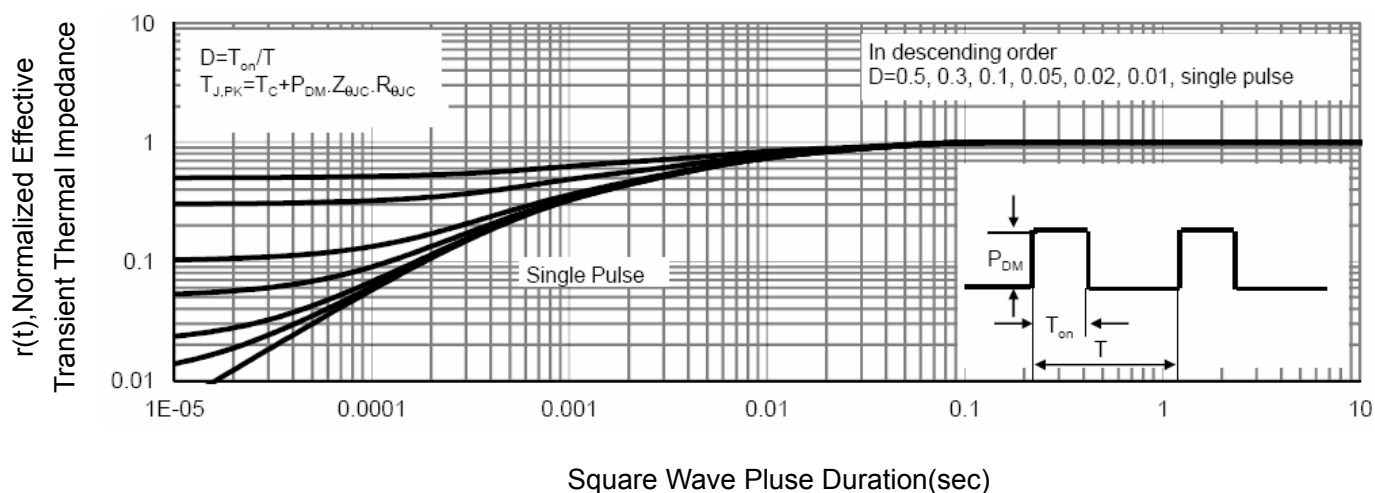
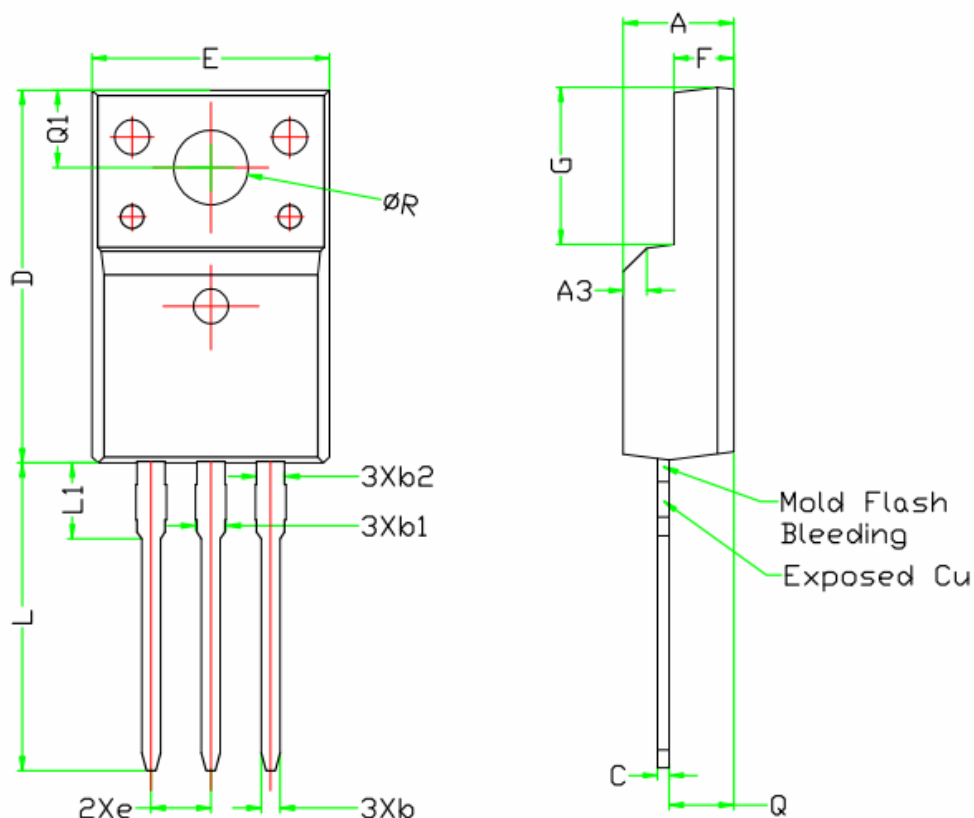


Figure 11 Normalized Maximum Transient Thermal Impedance

## TO-220F Package Information



| symbol | DIMENSIONS |       |       |
|--------|------------|-------|-------|
|        | Min.       | Nom.  | Max.  |
| A      | 4.60       | 4.70  | 4.80  |
| b      | 0.70       | 0.80  | 0.91  |
| b1     | 1.20       | 1.30  | 1.47  |
| b2     | 1.10       | 1.20  | 1.30  |
| C      | 0.45       | 0.50  | 0.63  |
| D      | 15.80      | 15.87 | 15.97 |
| e      | 2.54       |       |       |
| E      | 10.00      | 10.10 | 10.30 |
| F      | 2.44       | 2.54  | 2.64  |
| G      | 6.50       | 6.70  | 6.90  |
| L      | 12.90      | 13.10 | 13.30 |
| L1     | 3.13       | 3.23  | 3.33  |
| Q      | 2.65       | 2.75  | 2.85  |
| Q1     | 3.20       | 3.30  | 3.40  |
| ØR     | 3.06       | 3.16  | 3.26  |

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